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Atty Docket #:
SC0969AM

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying part(ies):
Saat Shukri Embong
Chee Chew Hiong

2. Name and address of receiving party(ies):
Name: Semiconductor Components Industries, LLC
Internal Address: Patent Administration Dept. - A230
Street Address: 5005 East McDowell Road
City: Phoenix State: AZ ZIP: 85008
Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance:
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Execution date of conveyance: October 17, 2000

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: October 17, 2000

A. Patent Application No.(s):
09/728390

B. Patent No.(s):

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: Semiconductor Components Industries, LLC
Internal Address: Patent Administration Dept - MD A230
Street Address: P.O. Box 62890
City, State, Zip: Phoenix, AZ 85082-2890

6. Total number of applications and patents involved: 1

7. Total fee (37 C.F.R. 3.41).. $ 40.00
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8. Deposit account number: 501086
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To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Michael T. Wallace	45,420	Michael T. Wallace	11-30-2000
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12/20/2000 AAHMED1 00000248 501086 09728390
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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we, Saat Shukri Embong of Kuala Terengganu, MALAYSIAA; and Chee Chew Hiong of Negeri Sembilan, MALAYSIA, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto Semiconductor Components Industries, LLC (SCI), a corporation of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States of America in and to certain inventions relating to improvements in BALL-LESS CLIP BONDING (Attorney Docket No. SC0969AM), described, illustrated, and claimed in an application for Letters Patent of the United States of America executed by us, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation, or reissue thereof.

We hereby also sell, assign, and transfer unto SCI, the entire right, title, and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the inventions and the applications for Letters Patent in foreign countries, and we further authorize SCI to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation, or reissue, to SCI, for the sole use and behalf of SCI, its successors, assigns, and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as they would have been held and enjoyed by us had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to SCI.

We agree that, when requested, we will, without charge to SCI, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in SCI, its successors, assigns, and legal representatives or nominees.

We covenant with SCI, its successors, assigns, and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

Saat Shukri Embong

Date: October 17, 2000

Witnessed by:
Signature

WONG CHIN WAI
Printed Name

Address correspondence concerning this document to: Semiconductor Components Industries, LLC, Patent Administration Dept - MD A230, P.O. Box 62890, Phoenix, AZ 85082-2890.

Chee Chew Hiong

Date: 17 / OCT/ 00

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